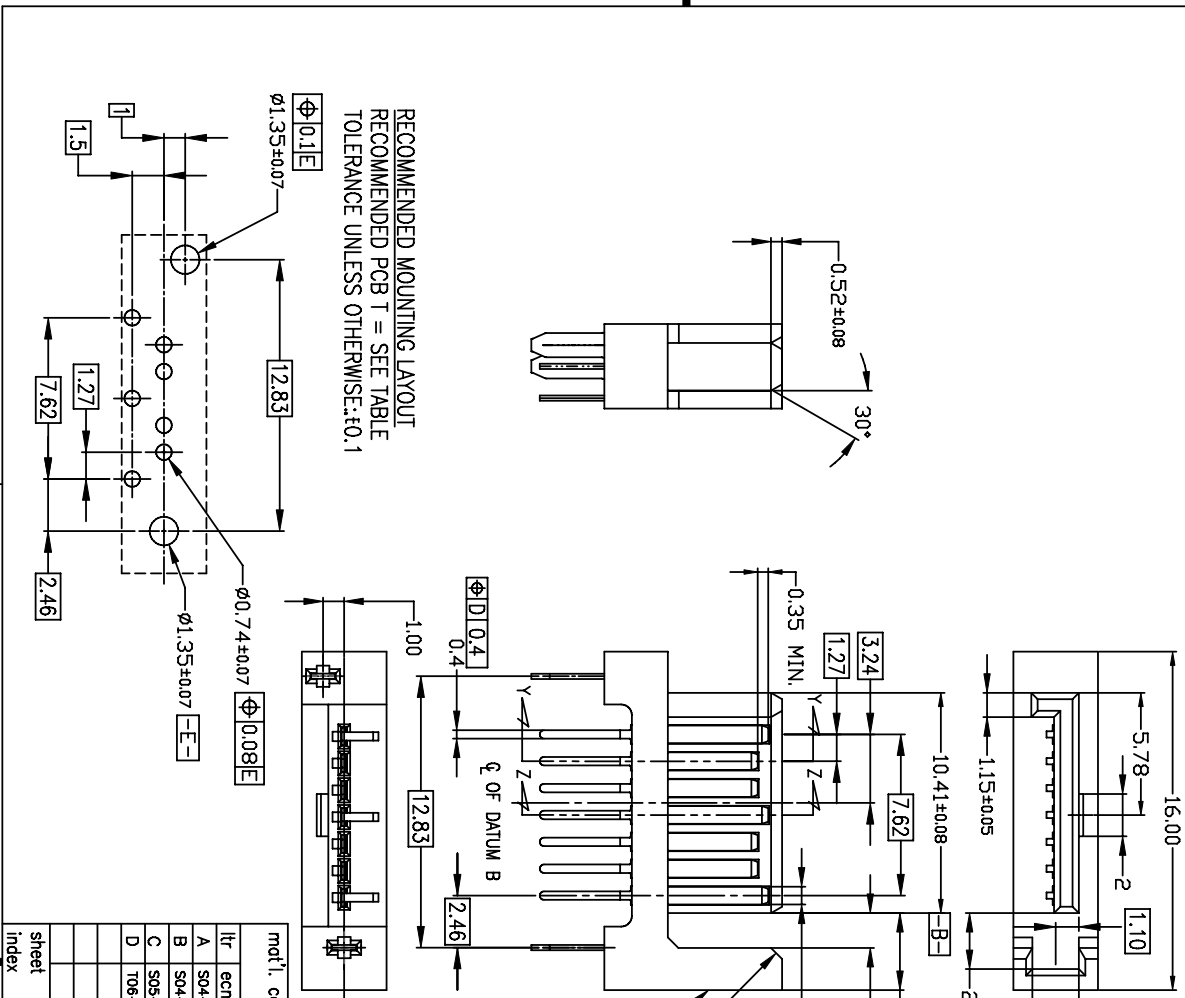
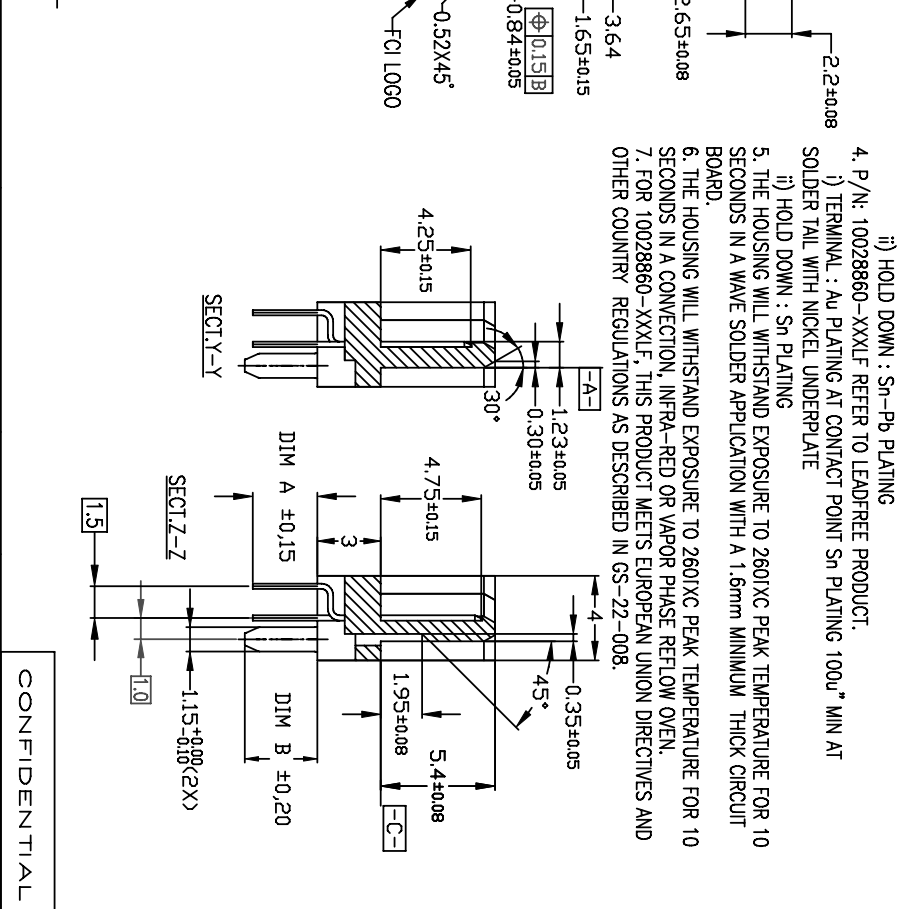




PRODUCT NO.	DIM A	DIM B	PLATING ON CONTACT	RECOMMENDED PCB THK.
10028860-003	3.05	3.43	15u GOLD	2.36mm (.093")
10028860-003LF	3.05	3.43	15u GOLD	2.36mm (.093")
10028860-013LF	3.05	3.43	30u GOLD	2.36mm (.093")



mat'l. code	ecn no.	dr	date	lineor	tolerances unless otherwise specified	CUSTOMER COPY	title	product family	EDGE CARD	code
A	S04-0217	HLW	10/18/04	linear	X ± 0.38		S-ATA SIGNAL PLUG			
B	S04-0249	HLW	11/19/04	linear	.XX ± 0.25		DIP VERTICAL TYPE ASS'Y			
C	S05-0048	YSS	02/22/05	angles	0 ± 0.15					
D	106-0135	S.Lin	07/17/06	dr	0 ± 0.2					
				engr	JPEH	06/25/03				
				chr	YEO SS	02/22/05				
				appr	JOEY NG	02/22/05				
sheet	revision									
index	sheet									



NOTE
 1. THIS PRODUCT MEETS THE SATA SPEC REV.1.00
 2. MATERIAL - i) HOUSING : HIGH TEMP. THERMOPLASTIC UL94V-0
 ii) TERMINAL : COPPER ALLOY
 iii) HOLD DOWN : COPPER ALLOY
 3. FINISH - i) TERMINAL : Au PLATING AT CONTACT POINT Sn-Pb PLATING 100u"
 MIN AT SOLDER TAIL WITH NICKEL UNDERPLATE
 ii) HOLD DOWN : Sn-Pb PLATING
 4. P/N: 10028860-XXXX REFER TO LEADFREE PRODUCT.
 i) TERMINAL : Au PLATING AT CONTACT POINT Sn PLATING 100u" MIN AT SOLDER TAIL WITH NICKEL UNDERPLATE
 ii) HOLD DOWN : Sn PLATING
 5. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6mm MINIMUM THICK CIRCUIT BOARD.
 6. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A CONNECTION, INFRA-RED OR VAPOR PHASE REFLOW OVEN.
 7. FOR 10028860-XXXX, THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.

CONFIDENTIAL

ACAD

code code

sheet 1 of 1